GridPP51 & SWIFT-HEP07





AGENDA

1. A brief introduction to BIOS IT

2. Technology Update: Covering

- 4TH & 5TH Gen AMD EPYC Processors
- H13 Turin drop-in support Roadmap
- **5**th Gen Intel Processors
- X14 Supermicro Roadmap
- Ampere Processors & Solutions
- IBM Power10
- Storage Technologies
- Liquid Cooling

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BIOS IT

BIOS IT is a design house, systems builder and integrated solution provider for high performance computing, storage & Networking.

Our engineering resources and BIOS IT Labs allow us to select the best components and newest technologies based on specific customer goals and budgets.

Access to our Labs, both remotely and on-site at our facilities is available.



supplier

Case study: UK company BIOS-IT outfitting new CERN data centre

Policy paper

UK strategy for engagement with CERN: unlocking the full potential of UK membership of CERN Published 4 October 2023

By The Numbers



Quality Management

ISO 14001:2015

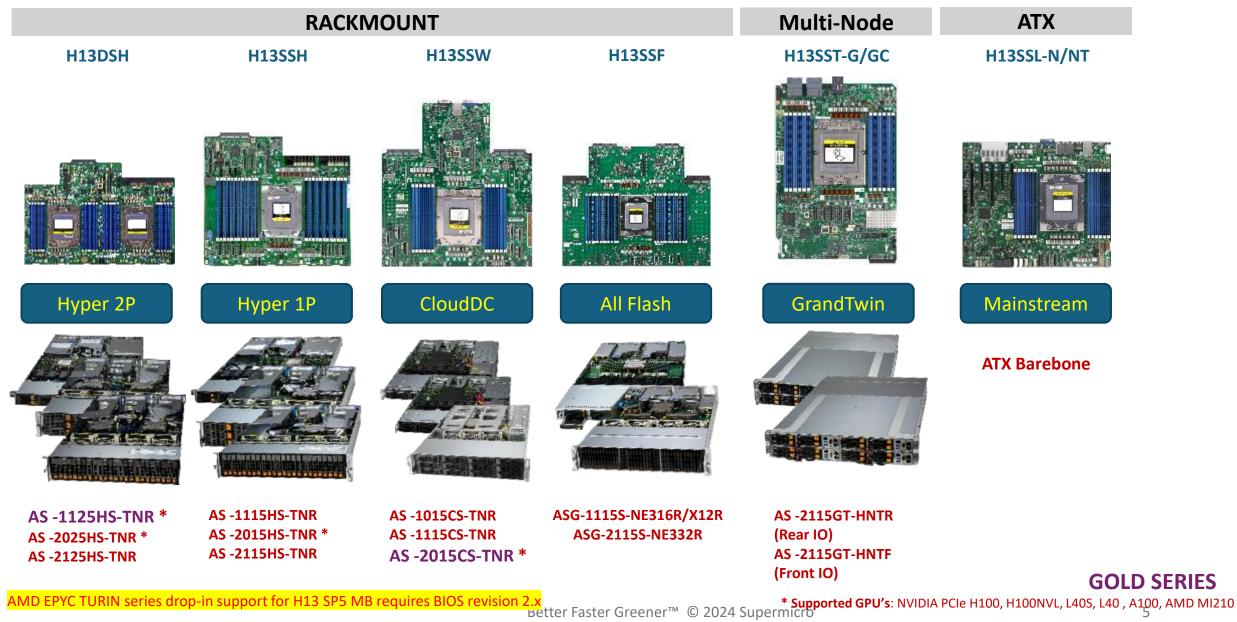
Environmental Management System



4TH & 5TH GENERATION AMD EPYC CPUs

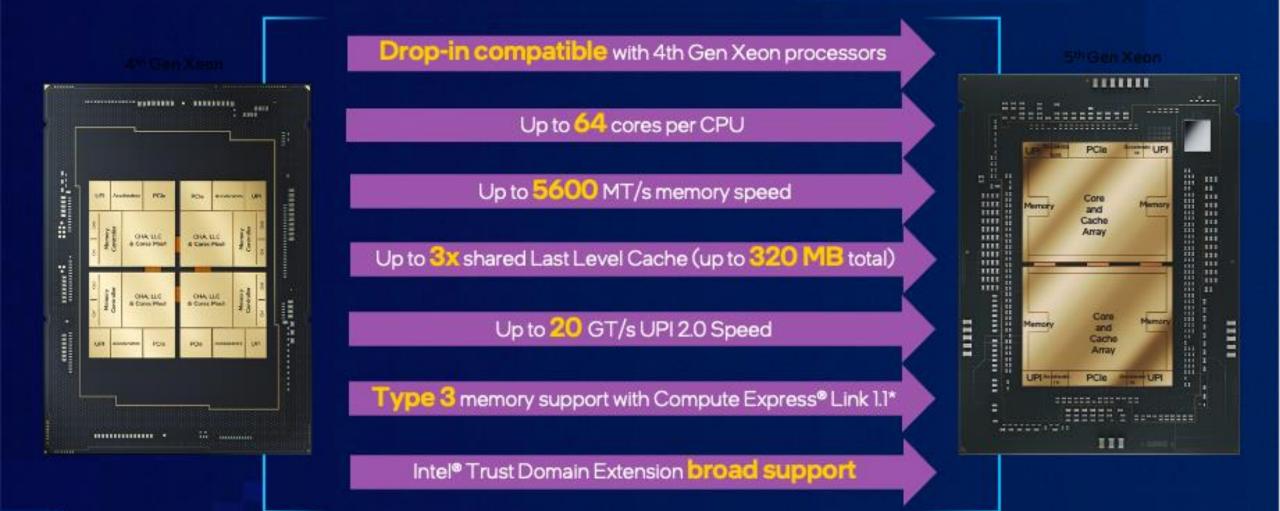
Spec	Socket SP5 EPYC Turin Classic CPU	Socket SP5 EPYC Turin Dense CPU	Socket SP5 EPYC Genoa CPU	Socket SP5 EPYC Bergamo CPU				
CPU TDP	200W ~ <mark>500W</mark>	320W ~ 500W	200W ~ 400W	320W ~ 400W				
Socket	Socket SP5 (LGA 6096)							
Scalability	1S, 2S							
Cores	16C up to 128C / 256 threads per socket	96C up to 192C / 384 threads per socket	16C up to 96C / 192 threads per socket	112C up to 128C / 256 threads per socket				
Manager	12 channels DI RDIMM, 3DS RD	DR5 per socket NMM, <mark>MRDIMM</mark>	12 channels DDR5 per socket RDIMM, 3DS RDIMM					
Memory		p to 4400 MT/s (Single Rank) GB 3DS RDIMM)	1DPC = up to 4800, 2DPC = up to 4000 MT/s Up to 6TB (256GB 3DS RDIMM)					
Cache	Expected ~22% improvement in	per 16 cores/CCD	L2: 1MB per core L3: 32MB per 8 cores/CCD Up to 384MB (12 CCD)	L2: 1MB per core L3: 16MB per 8 cores/CCX (2 CCX/CCD) Up to 256MB (8 CCD)				
	power efficienc	PCle 5.0	(32 GT/s)					
<u>PCIe</u>		PCIes PCIe3 PCIes PLanes PCIe3 (6 per socket) bifurcations supported down to x4	1S: 128 lanes PCle5 + up to 8 lanes PCle3 2S: 128 lanes (160 w/ 3-link XGMI) PCle5 + 12 lanes PCle3 (6 per socket) CXL: 64 lanes support CXL 1.1+ with bifurcations supported down to x4					
SATA		1S: up to 2S: up to 32 SATA	32 SATAs As (16 per socket)					
Process	5nm+ (<mark>Zen5</mark>)	3nm (Zen5c)	5nm+ (Zen4)	5nm+ (Zen4c)				

A+ H13 System Turin drop-in support



5th Gen Intel® Xeon® Processors

Platform enhancements delivering significant gains at the same power envelope¹



5

X14 Supermicro Roadmap



	Q1 2024		(Q2 2024		(Q3 2024			Q4 2024		Q1 2025		Q2 2025				
	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sept	Oct	Nov	Dec	Jan	Feb	Mar	Apr	May	Jun
	Sampling				_	Hyper: 1U/2U Rackmount Enterprise. Consolidating compute, storage, expansion, network flexibility in one server line. (DP, 32DIMM, AIOM) (UP, 16DIMM, AIOM) – MP: May												
Rackmounts	Sampling				Lotter.	DC-MHS: 1U/2U Rackmount Cloud. Cost effective DP solution for high volume cloud deployments. (DP, 32DIMM, Dual AIOM, DC-SCM) (UP, 16DIMM, AIOM) – MP: May												
	Sampling			pling		WIO: 1U/2U Rackmount. Mainstream/General Purpose with low TCO (UP, 8DIMM, SATA native). - MP: May												
Twin Series	Sampling Sampling				-		Twin 2U IP: May	Multi-no	de. Highe	est 2U no	ode densi	ty with u	p to 4 no	des per (enclosure	. (DP, 16	DIMM, A	IOM)
Twill Series					(Change)	GrandTwin: 2U Flexible front or rear IO UP servers in 4 node or 2 node design stack up. (UP, 16DIMM, AIOM) – MP: May												
Samplir					SuperBlade: 8U 20-node, Highest density for Cloud, HPC, Enterprise (DP, 16DIMM, AIOM, E1.S) – MP: May													
SuperBlade				Samplir	(Then	Su	perBlade	: 6U 10-n	ode, Max	timum N	lemory v	vith GPU	(DP 32D	IMM/UP	16DIMM	, PCle, E	3.S) – MP:	May
Storage Samplin Petascale (DC-MHS): 1U/2U High Density All-Flash NVMe per MP: May					e perforn	nance sto	orage (DP	, 32DIMI	M, EDSFF)									
	Intel Xeon 6 SRF-SP (QS) Intel Xeon 6 SRF-SP (MP)																	

AMPERE Processor Comparison

Specification	Ampere Altra	Ampere Altra Max	Ampere One	
Architecture	ARM	ARM	ARM	
Socket Compatible Packages	4926-Pin FCLGA	4926-Pin FCLGA	5964-Pin FCLGA	
Cores	Up to 80	Up to 128	Up to 192	
Max Frequency	3.3 GHz	3.0 GHz	3.3 GHz	
Memory Support	DDR4-3200	DDR4-3200	DDR5-4800	
Memory Capacity	Up to 4 TB	Up to 4 TB	Up to 8 TB	
Memory Channels	8	8	8	
TDP	Up to 250W	Up to 250W	Up to 300W	
PCle Gen	Gen4	Gen4	Gen5	
Process Technology	7nm	7nm	5nm	

AM

AMPONE and AMPERE Ultra Max solution



8 x 3.5"/2.5" SATA + 4 x SATA/ NVMe Hybrid

2 x PCIe Gen5 x16 expansion slots 3 /4 PCIe Gen5 x 8 expansion slots 2 x OCP 3.0 Gen5 x16 mezzanine slots



2 x PCIe Gen5 x16 expansion slots

2 x OCP 3.0 Gen5 x16 mezzanine slots



4 x 3.5"/ 2.5" NVMe/SATA Hot-swap Bays

2 x 800W 80+ Platinum Power Supply

2 x 1300W 80+ Platinum Power Supply

Processor Comparison - Power10 vs Xeon SP Platinum – AMD EPYC Genoa

Features	AMD EPYC 4 th Generation	Sapphire Rapids (4th Generation Intel® Xeon® Scalable Processors)	Power 10 DCM	Power 10 SCM	
Processor	AMD EPYC 9654	Intel® Xeon® Platinum 8490H Processor	IBM Power 10 (Based on E1050 24C Processor)	IBM Power 10 (Based on E1080 15C Processor)	
Lithography	5 nm	Intel 7 (aka 10nmESF)	7 nm	7 nm	
Available Max Cores per Processor	96	60	24	15	
Max Threads per Core	2	2	8	8	
L3 Cache Per Core	4 MB	1.875 MB	8 MB	8 MB	
Max Core Configuration	192	480 960 (16S HPE 3200 server)	96	240	
Maximum Memory Speed	Up to DDR5 4800 MHz	Up to DDR5 4800 MHz Up to DDR5 4400 MHz(2 DPC)	2933 MHz	2933 MHz	
Memory Channels Per Socket	12	8	16	16	
Max Memory Configuration	12 TB	Up to 32TB (16S)	16TB	64 TB	
Theoritical Memory Bandwidth/Processor	460 GB/s	307 GB/s (282 w/2 DPC)	409 GB/s	409 GB/s	
IO Technology	PCIe 5.0	PCIe 5.0	PCIe4.0(PCIe 5.0 Supported)	PCIe4.0(PCIe 5.0 Supported)	
Scalability			2S-4S	16S	

Power10 : no compromise between Scalability, Memory Size & Bandwidth , Core Performance

Why Power is different infrastructure ?

A complete design, all components are integrated single solution and unique architecture for **data processing**

- Processor, Memory Xbar, Microcode, Virtualization, OS, ...
- Infrastructure Management
- System Software, Cloud capabilities
- RAS and Security
- I/O connectivity (Storage, Network)
- Unique Flexibility features (PEP, LUK,
- Simple operations
- For Long term investment

Infrastructure matters for:

Security, Performance, Reliability, Flexibility, Agility, sustainability and TCO

We design technology to help you drive business

2021: IBM World's First 2 nanometers Chip Technology 🕒 YouTube



Infrastructure is critical and it's only 25% of IT spending

SuperStorage LFF Storage Family

Completed LFF Storage Platform for Storage-Centric Data Center from Edge to Cloud

Storage Capacity



Intel X13 and AMD H13 Based Top Loading 90/60 Bay storage



Single Node Configuration



Dual Node Configuration

Processor Support

Dual Gen5 processors (Intel SPR)

Memory Capacity

16x DIMM slots, DDR5-4800

Expansion

3x PCI-E 5.0 x16

Networking & I/O

- 2x 10GBase-T LAN ports
- 1x RJ45 Dedicated IPMI LAN port and 2x USB 3.0 ports, 1x VGA ports and 1x Serial port

Drive Bays

- 60 or 90x Hot-swappable 2.5" or 3.5" drive bays (SAS3/SATA3)
- 2x rear Hot-swappable 2.5" SATA drive bays
- 2 onboard PCIe x2 M.2 slots and 2 internal slim SATA SSD slots
- 4 rear NVMe U.2 bays for cache support (optional)

Storage Controller

- Broadcom SAS 3816 AOM, 3816 AOC (IT mode)
- Broadcom SAS 3916, 3908 AOC (HW RAID mode)

System Cooling

6x Heavy duty counter-rotate redundant PWM cooling fans

Power Supply

2x 2000W or 2600W High-efficiency (Titanium level, 80%) redundant supply

System Management

Built-in Server management tool (IPMI 2.0, KVM/media over LAN) with dedicated LAN port

Dimensions

- 60 Bay : 17.68" (W) x 6.9" (H) x 34.1" (D)
- 90 Bay : 17.68" (W) x 6.9" (H) x 42.9" (D)

Subject to change without notice

Specifications

All Flash Storage server

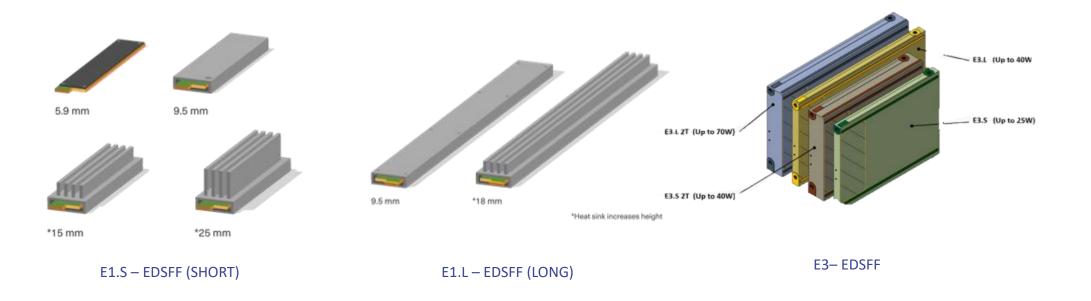
Revolutionary Petascale Nvme



Higher-Performance

- PCle Gen 5 x4: ~15.8GB/s
- Samsung PM1743: S/R 13GB/s, S/W 6.6GB/s
- PCIe Gen 4 x4: ~7.88GB/S
- Samsung PM1733: S/R 7GB/s, S/W 3.5GB/s
- Higher Capacities
 - up to 15.36TB and 30TB
- Cost per GB parity vs SATA
 - 960GB, 1920GB, 3840GB, 7680GB
- EDSFF Form Factors
 - E3.S
- 1U front-loading all-flash storage server
- 24 E1.S NVMe drives and PCIe 5.0
- Peak performance of 4.44 million IOPS (random 4k reads)
- At 99.5µs in latency
- Writes 4.2 million IOPS (4.2 million IOPS at 64.8μs)

EDSFF FORM FACTORS



Why a customer would want an E1.S or an E1.L SSD

- The E1.S is space in a compact server
- The E1.L has a larger cooling surface, which will allow for higher operating temperatures.
- Tradeoff between the different widths available

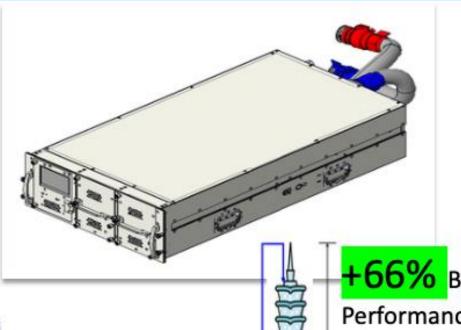
Product	Width of Enclosure	Recommended sustained power	Length
E1.S	5.9mm	12 watts	111.49mm
E1.S	9.5mm	20 watts	118.75mm
E1.S	15mm	20+ watts	118.75mm
E1.S	25mm	25+ watts	118.75mm
E1.L	9.5mm	25 watts	318.75mm
E1.L	18mm	40 watts	318.75mm

Supermicro DLC Solution -- CDU

- CDU: Cooling Distribution Unit
 - High Performance
 - User Friendly
 - Robust and Reliable
- Replace pump in 2 mins
- Replace PSU in 1 mins
- More 66% pressure head supported
- User friendly maintains
- Pressure/flow rate/leakage monitor
- Control remotely or Touch panel
- Non-Condensation Design







SUPERMIC

Save Money via Liquid Cooling

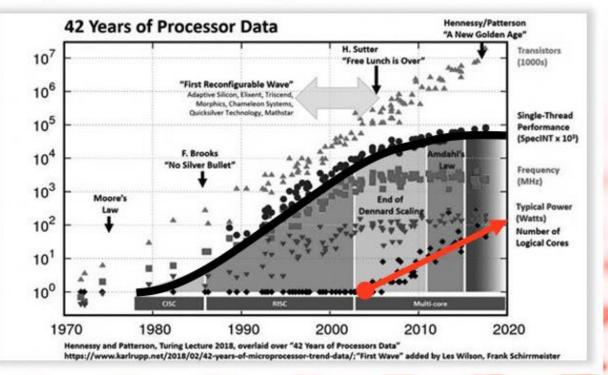
Item	Air Cooled - Traditional DC	Air Cooled - Modern DC	Cooling Tower with DLC (Cold Water)	Cooling Tower with DLC (Warm Water)	
Supply-Return-WB (*C)	Supply-Return-WB (°C) N/A		30-25-22	42-37-22	
Process Fluid Flow (GPM)	Depends on DC design	Depends on DC design	1,865	1,865	
Temperature Range (°C)	N/A	N/A	5	5	
IT Total Power (MW)	2.45	2.45	2.21	2.21	
Server Cooling Type	Air	Air	Liquid	Liquid	
Facility Cooling Power Cons. (kW)	2450	1225	551	172	
Gross PUE	2	1.5	1.25	1.08	
	Unite	ed States Electricity Cost \$0.20	/ kWh		
Cooling Electricity Cost (USD) per 5 years	21.5	10.7	4.8	1.5	
IT Electricity Cost (USD) per 5 years	21.5	21.5	19.4	19.4	
Total Cost (Cooling + IT)	42.9	32.2	24.2	20.9	
Total Savings (Liquid vs Air) mil USD	N/A	N/A	18.7	22.1	

Germany Electricity Cost \$0.52 / kWh							
Total Cost (Cooling + IT) 111.6 83.7 62.9 54.3							
Total Savings (Liquid vs Air)	N/A	N/A	48.7	57.3			
Japan Electricity Cost \$0.25 / kWh							

Total Cost (Cooling + IT)	53.7	40.2	30.2	26.1				
Total Savings (Liquid vs Air)	N/A	N/A	23.4	27.6				

UK Electricity Cost \$0.47 / kWh						
Total Cost (Cooling + IT)	100.9	75.7	56.8	49.0		
Total Savings (Liquid vs Air)	N/A	N/A	44.0	51.8		

Traditional Techniques No Longer Scale



Turbo Frequency Hyperthreading Scale Up Accelerators

Power Optimized Consistent Performance

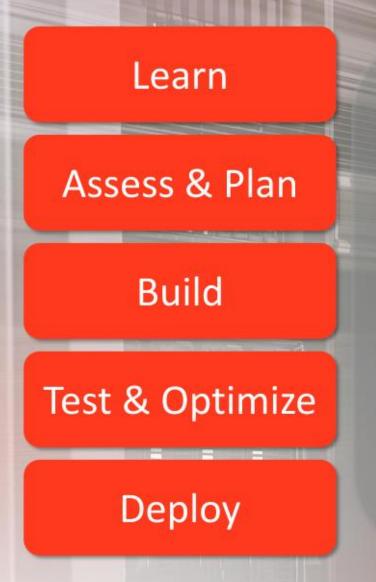
Linear Core Scaling

High Performance General-Purpose Cores

Paradigm Shift



Get Started Now with Cloud Native Processors



• Learn how to design with performance/rack metrics: https://amperecomputing.com/home/increase-data-center-efficiency

Browse Ampere Ready software references:
https://amperecomputing.com/solution

 Use our workload and solutions briefs: https://amperecomputing.com/briefs

 Join the Ampere Developer Community: https://community.amperecomputing.com

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